

FEATURE

- High-Side Switching
- Low On-Resistance
- Low Threshold
- Fast Switching Speed
- ESD protected

APPLICATIONS

- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems
- Power Supply Converter Circuits
- Load/Power Switching Cell Phones, Pagers

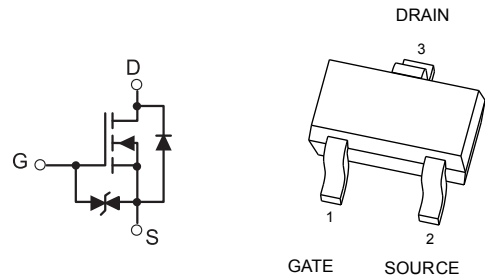
Marking

- Marking: C

N-Channel Power MOSFET

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
20V	700mΩ@4.5V	500mA
	850mΩ@2.5V	

PACKAGE



SOT-523

Maximum ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source voltage	V_{DSS}	20	V
Gate-Source Voltage	V_{GS}	±10	
Drain Current-Continuous	$I_{D(DC)}$	500	mA
Drain Current -Pulsed(note1)	$I_{DM(pulse)}$	1000	
Power Dissipation (note 2 , $T_a=25^\circ\text{C}$)	P_D	150	mW
Maximum Power Dissipation (note 3 , $T_c=25^\circ\text{C}$)		275	
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	833	°C/W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	455	
Storage Temperature	T_j	150	°C
Junction Temperature	T_{stg}	-55 ~+150	



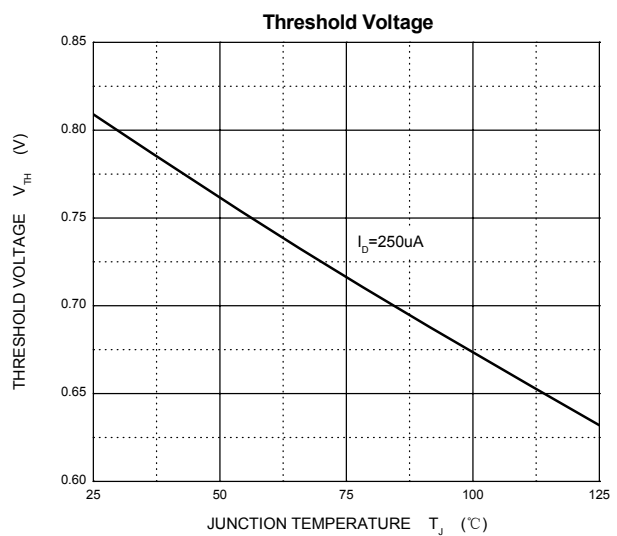
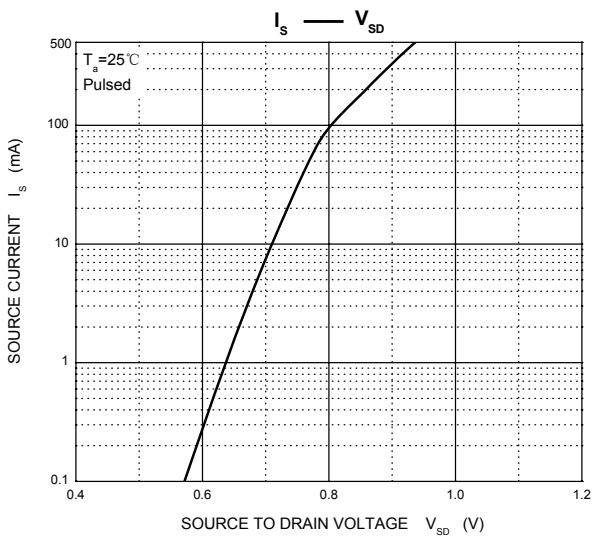
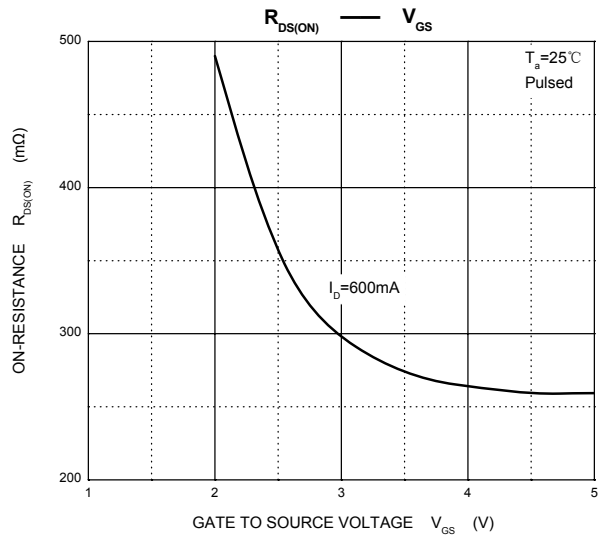
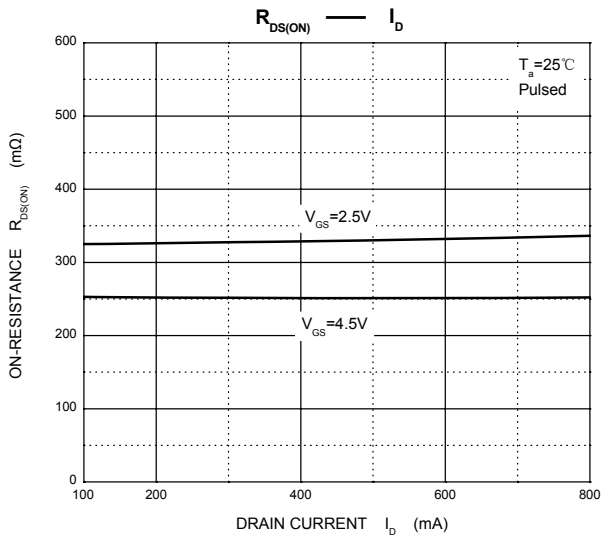
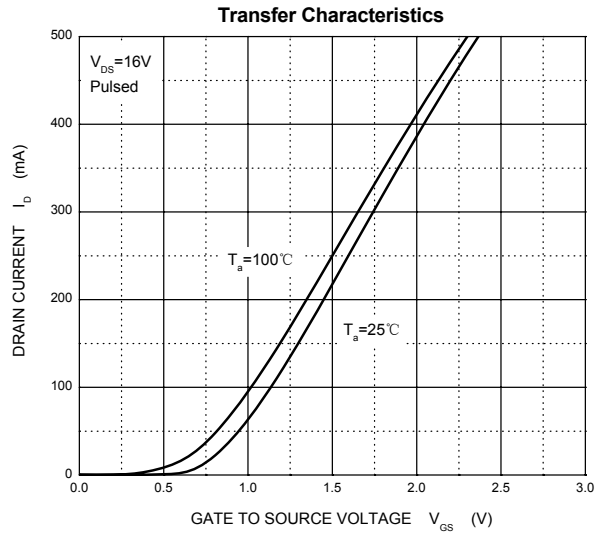
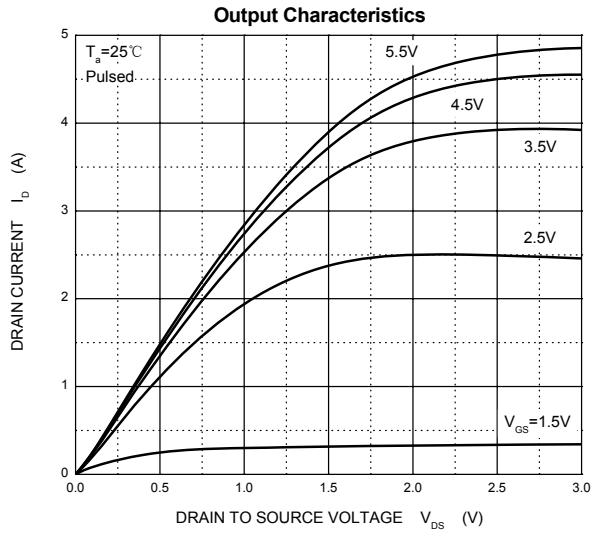
Ta=25 °C unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
On/Off States						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	20			V
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.45	0.8	1.2	
Gate-Body Leakage Current	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 4.5V$			± 1	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 16V, V_{GS} = 0V$			100	nA
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 600mA$		250	700	m Ω
		$V_{GS} = 2.5V, I_D = 500mA$		330	850	
Forward Transconductance	g_{fs}	$V_{DS} = 10V, I_D = 400mA$		1		S
Dynamic Characteristics						
Input Capacitance (note 4)	C_{iss}	$V_{DS} = 16V, V_{GS} = 0V, f = 1MHz$		100		pF
Output Capacitance (note 4)	C_{oss}			16		
Reverse Transfer Capacitance (note 4)	C_{rss}			12		
Total Gate Charge	Q_g	$V_{DS} = 10V, V_{GS} = 4.5V, I_D = 250mA$		750		nC
Gate-Source Charge	Q_{gs}			75		
Gate-Drain Charge	Q_{gd}			225		
Switching Times (note 4)						
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 10V, R_L = 47\Omega, I_D = 200mA, V_{GS} = 4.5V, R_G = 10\Omega$		5		nS
Rise Time	t_r			5		
Turn-Off Delay Time	$t_{d(off)}$			25		
Fall Time	t_f			11		
Drain-Source Diode Characteristics						
Drain-Source Diode Forward Voltage (note 5)	V_{SD}	$I_S = 0.15A, V_{GS} = 0V$			1.2	V

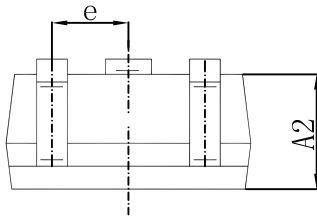
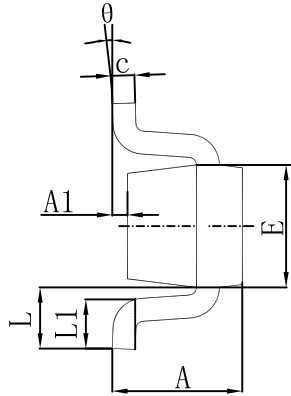
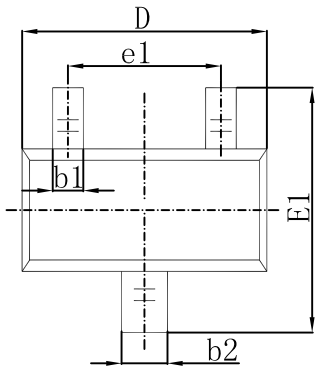
Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. This test is performed with no heat sink at Ta=25°C.
3. This test is performed with infinite heat sink at Tc=25°C.
4. These parameters have no way to verify.
5. Pulse Test : Pulse Width≤300μs, Duty Cycle≤0.5%.

Typical Characteristics

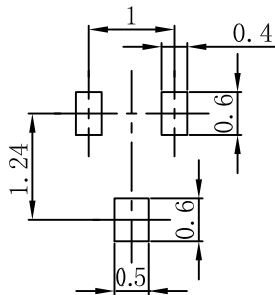


SOT-523 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.000	0.100	0.000	0.004
A2	0.700	0.800	0.028	0.031
b1	0.150	0.250	0.006	0.010
b2	0.250	0.350	0.010	0.014
c	0.100	0.200	0.004	0.008
D	1.500	1.700	0.059	0.067
E	0.700	0.900	0.028	0.035
E1	1.450	1.750	0.057	0.069
e	0.500 TYP.		0.020 TYP.	
e1	0.900	1.100	0.035	0.043
L	0.400 REF.		0.016 REF.	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

SOT-523 Suggested Pad Layout



Note:
 1. Controlling dimension: in millimeters.
 2. General tolerance: ±0.05mm.
 3. The pad layout is for reference purposes only.